



Material Content Data Sheet



Sales Product Name				IPB60R045P7		Issued		16. July 2019	
MA#				MA005348072					
Package				PG-TO263-3-2		Weight*		1565.00 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	13.676	0.87	0.87	8739	8739	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58		
	non noble metal	iron	7439-89-6	0.304	0.02		195		
	non noble metal	copper	7440-50-8	304.026	19.43	19.46	194265	194518	
	non noble metal	aluminium	7429-90-5	5.655	0.36	0.36	3614	3614	
wire	non noble metal	aluminium	7429-90-5	5.655	0.36	0.36	3614	3614	
encapsulation	organic material	carbon black	1333-86-4	10.119	0.65		6466		
	plastics	epoxy resin	-	111.304	7.11		71120		
	inorganic material	silicondioxide	60676-86-0	553.146	35.35	43.11	353448	431034	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6170	6170	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147	
solder	non noble metal	tin	7440-31-5	0.168	0.01		108		
	noble metal	silver	7440-22-4	0.210	0.01		134		
	non noble metal	lead	7439-92-1	8.037	0.51	0.53	5136	5378	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105		
	non noble metal	iron	7439-89-6	0.548	0.04		350		
	non noble metal	copper	7440-50-8	547.666	34.99	35.04	349945	350400	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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